



## Material Content Data Sheet



<b>Sales Product Name</b>				IPG16N10S4-61A		<b>Issued</b>		4. July 2019	
<b>MA#</b>				MA002213674					
<b>Package</b>				PG-TDSON-8-10		<b>Weight*</b>		98.78 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip_1	inorganic material	silicon	7440-21-3	0.692	0.70	0.70	7005	7005	
chip_2	inorganic material	silicon	7440-21-3	0.692	0.70	0.70	7005	7005	
leadframe	inorganic material	phosphorus	7723-14-0	0.013	0.01		133		
	non noble metal	iron	7439-89-6	0.044	0.04		443		
	non noble metal	copper	7440-50-8	43.681	44.24	44.29	442209	442785	
	non noble metal	aluminium	7429-90-5	0.798	0.81	0.81	8083	8083	
wire	non noble metal	aluminium	7429-90-5	0.798	0.81	0.81	8083	8083	
encapsulation	organic material	carbon black	1333-86-4	0.092	0.09		935		
	plastics	epoxy resin	-	6.561	6.64		66417		
	inorganic material	silicondioxide	60676-86-0	39.549	40.04	46.77	400373	467725	
leadfinish	non noble metal	tin	7440-31-5	1.396	1.41	1.41	14137	14137	
plating	inorganic material	phosphorus	7723-14-0	0.001	0.00		15		
	non noble metal	nickel	7440-02-0	0.603	0.61	0.61	6105	6120	
solder	non noble metal	tin	7440-31-5	0.039	0.04		396		
	noble metal	silver	7440-22-4	0.049	0.05		495		
	non noble metal	lead	7439-92-1	1.866	1.89	1.98	18892	19783	
heatspreader	inorganic material	phosphorus	7723-14-0	0.001	0.00		8		
	non noble metal	iron	7439-89-6	0.003	0.00		27		
	non noble metal	copper	7440-50-8	2.699	2.73	2.73	27322	27357	
*deviation	< 10%		Sum in total:			100.00		1000000	

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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